



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-08
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TS512AIDT	JDO7*0402BU6	A	BO2A	2016-08-08
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	6.5X6.1X2.3	2	gull wing	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20thJune 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	JDO7*0402BU6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	2.363	mg	supplier	DIE	Silicon (Si)	7440-21-3		2.311	mg	977994	28888
SILICON DIE				supplier	METALLIZATION	Aluminium (Al)	7429-90-5		0.029	mg	12273	363
SILICON DIE				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.01	mg	4232	125
SILICON DIE				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.013	mg	5501	163
Leadframe	Copper and its alloy	33.505	mg	Supplier	frame alloy	Copper (Cu)	7440-50-8		33.461	mg	993881	418263
Leadframe				Supplier		Iron (Fe)	7439-89-6		0.016	mg	475	200
Leadframe				Supplier		Iron Phosphide (FeP)	26508-33-8		0.028	mg	832	350
Leadframe	Other Organic Material	0.162	mg	Supplier	frame coating	Nickel (Ni)	7440-02-0		0.152	mg	4515	1900
Leadframe				Supplier		Palladium (Pd)	7440-05-3		0.005	mg	149	63
Leadframe				Supplier		Gold (Au)	7440-57-5		0.005	mg	149	63
Die Attach	Other Inorganic Material	0.195	mg	Supplier	glue	Silver (Ag)	7440-22-4		0.177	mg	907692	2213
Die Attach				Supplier		acrylate	Proprietary		0.01	mg	51282	125
Die Attach				Supplier		Methacrylate	Proprietary		0.008	mg	41026	100
Bonding wire	Other inorganic materials	0.042	mg	Supplier	Bonding wire	Copper (Cu)	7440-50-8		0.042	mg	1000000	525
Encapsulation	Other Organic Materials	43.733	mg	Supplier	Moulding Compound	Epoxy Resin	25068-38-6		3.28	mg	75001	41000
Encapsulation				Supplier		Phenol Resin	29690-82-2		2.187	mg	50008	27338
Encapsulation				Supplier		Silica, vitreous	60676-86-0		37.872	mg	865982	473400
Encapsulation				Supplier		Carbon black	1333-86-4		0.219	mg	5008	2738
Encapsulation				supplier		Bismuth (Bi)	7440-69-9		0.175	mg	4002	2188